

低消費電力SRAM 発注型名

R1 L V 5256 E SA - 5 S I #B1

R1 L P 04 08 D SP - 5 S I #B1

RM L V 04 16 E G SB - 4 S 2 #A A 1

RENESAS Memory

Chip configuration

| | |
|----------|---------------------|
| L | LPSRAM, Single chip |
| W | LPSRAM, Two chips |

Operating Voltage

| | |
|----------|----|
| V | 3V |
| P | 5V |

Memory Density

| | |
|-------------|------------|
| 5256 | 256Kb (x8) |
| 01 | 1Mb |
| 02 | 2Mb |
| 04 | 4Mb |
| 08 | 8Mb |
| 16 | 16Mb |
| 32 | 32Mb |
| 64 | 64Mb |

Bus Width

| | |
|-----------|-----|
| 08 | x8 |
| 16 | x16 |

Chip Generation

Industrial Grade

Package Type

| | |
|-----------|---|
| SA | TSOP-I (256Kb/8Mb/16Mb/32Mb/64Mb) sTSOP (1Mb/2Mb/4Mb) |
| SB | TSOP-II |
| SD | μTSOP |
| SF | TSOP-I (1Mb) |
| SP | SOP (256Kb, 4Mb) |
| SN | SOP (1Mb) |
| BG | FBGA |

Operating Temperature

| | |
|----------|------------|
| R | 0 ~ 70°C |
| I | -40 ~ 85°C |
| 2 | -40 ~ 85°C |

Packing

| | |
|----------|-----------------------------------|
| A | Tray |
| C | Magazine |
| H | Tape & Reel (TSOP-II, μTSOP, SOP) |
| K | Tape & Reel (FBGA, TSOP-I, sTSOP) |

Access time

| | |
|----------|-------|
| 5 | 55 ns |
| 4 | 45 ns |

Stand-by current / Data retention current

| | |
|----------|-------------------------|
| S | Low power version |
| U | Ultra Low power version |

Packing, Environmental

| | | |
|------------------|------------------|---------------|
| | Packing | Environmental |
| #B0 / #B1 | Tray or Magazine | Pb free |
| #S0 / #S1 | Tape & Reel | Pb free |

Assembly Site Rev. , etc.

Environment

| | |
|----------|--------------------------------|
| A | Pb free (pure-Tin plating) |
| C | Pb free (non-pure-Tin plating) |

| | |
|----------|-----------|
| 0 | Rev. Code |
| 1 | Rev. Code |

高速 4Mb SRAM 発注型名

R1 R W 04 16 D SB - 2 P I #D1

RENESAS Memory

Fast SRAM

Operation Voltage

| | |
|---|------|
| W | 3.3V |
| P | 5V |

Memory density

| | |
|----|-----|
| 04 | 4Mb |
|----|-----|

Bus Width

| | |
|----|-----|
| 08 | x8 |
| 16 | x16 |

Chip generation

Packing, Environmental

| | Packing | Environmental |
|-----------|----------------|---------------|
| #B0 / #B1 | Magazine (SOJ) | Pb free |
| #D0 / #D1 | Tray (TSOP) | Pb free |
| #S0 / #S1 | Tape & Reel | Pb free |

Operating Temperature

| | |
|---|------------|
| R | 0 ~ 70°C |
| I | -40 ~ 85°C |

Stand by current / Data retention current

| | |
|---|-------------------------|
| P | Standard |
| L | Low power version |
| S | Super Low power version |

Access time

| | |
|---|-------|
| 2 | 12 ns |
| 0 | 10 ns |

Package type

| | |
|----|---------|
| GE | SOJ |
| SB | TSOP-II |

低消費電力SRAMラインアップ (256Kb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|-----------------|---------|----------|-------------------|---------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.15μm Advanced | 256Kbit | 32K x 8 | R1LP5256ESA-5SI | R1LP5256ESA-5SI#B1 | TSOP-I (28) | Tray | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LP5256ESA-5SI#S1 | TSOP-I (28) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1LP5256ESP-5SI | R1LP5256ESP-5SI#B1 | SOP (28) | Magazine | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LP5256ESP-5SI#S1 | SOP (28) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| 0.15μm Advanced | 256Kbit | 32K x 8 | R1LV5256ESA-5SI | R1LV5256ESA-5SI#B1 | TSOP-I (28) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV5256ESA-5SI#S1 | TSOP-I (28) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1LV5256ESP-5SI | R1LV5256ESP-5SI#B1 | SOP (28) | Magazine | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV5256ESP-5SI#S1 | SOP (28) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

(注) マガジン(Magazine)、チューブ(Tube)、スティック(Stick)と呼ばれる容器を、ここではすべて「マガジン(Magazine)」と表記します。

低消費電力SRAMラインアップ (1Mb~2Mb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|-----------------|---------|----------|-------------------|---------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.15μm Advanced | 1Mbit | 128K x 8 | R1LP0108ESA-5SI | R1LP0108ESA-5SI#B1 | sTSOP (32) | Tray | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LP0108ESA-5SI#S1 | sTSOP (32) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1LP0108ESF-5SI | R1LP0108ESF-5SI#B1 | TSOP-I (32) | Tray | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Mar. 2031 |
| | | | | R1LP0108ESF-5SI#S1 | TSOP-I (32) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Mar. 2031 |
| | | | R1LP0108ESN-5SI | R1LP0108ESN-5SI#B1 | SOP (32) | Magazine | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LP0108ESN-5SI#S1 | SOP (32) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| 0.15μm Advanced | 1Mbit | 128K x 8 | R1LV0108ESA-5SI | R1LV0108ESA-5SI#B1 | sTSOP (32) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV0108ESA-5SI#S1 | sTSOP (32) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1LV0108ESF-5SI | R1LV0108ESF-5SI#B1 | TSOP-I (32) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Mar. 2031 |
| | | | | R1LV0108ESF-5SI#S1 | TSOP-I (32) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Mar. 2031 |
| | | | R1LV0108ESN-5SI | R1LV0108ESN-5SI#B1 | SOP (32) | Magazine | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV0108ESN-5SI#S1 | SOP (32) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| 0.15μm Advanced | 2Mbit | 256K x 8 | R1LV0208BSA-5SI | R1LV0208BSA-5SI#B1 | sTSOP (32) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV0208BSA-5SI#S1 | sTSOP (32) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 128K x16 | R1LV0216BSB-5SI | R1LV0216BSB-5SI#B1 | TSOP-II (44) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LV0216BSB-5SI#S1 | TSOP-II (44) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

低消費電力SRAMラインアップ (4Mb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|-----------------|---------|-----------|-------------------|----------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.15μm Advanced | 4Mbit | 512K x 8 | R1LP0408DSB-5SI | R1LP0408DSB-5SI#B1 | TSOP-II (32) | Tray | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Mar. 2031 |
| | | | | R1LP0408DSB-5SI#S1 | TSOP-II (32) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Mar. 2031 |
| | | | R1LP0408DSP-5SI | R1LP0408DSP-5SI#B1 | SOP (32) | Magazine | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1LP0408DSP-5SI#S1 | SOP (32) | Tape & Reel | 55ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| 0.11μm Advanced | 4Mbit | 512K x 8 | RMLV0408EGSA-4S2 | RMLV0408EGSA-4S2#AA1 | sTSOP (32) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0408EGSA-4S2#KA1 | sTSOP (32) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMLV0408EGSB-4S2 | RMLV0408EGSB-4S2#AA1 | TSOP-II (32) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Mar. 2031 |
| | | | | RMLV0408EGSB-4S2#HA1 | TSOP-II (32) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Mar. 2031 |
| | | | RMLV0408EGSP-4S2 | RMLV0408EGSP-4S2#CA1 | SOP (32) | Magazine | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0408EGSP-4S2#HA1 | SOP (32) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 256K x 16 | RMLV0414EGSB-4S2 | RMLV0414EGSB-4S2#AA1 | TSOP-II (44) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0414EGSB-4S2#HA1 | TSOP-II (44) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMLV0416EGBG-4S2 | RMLV0416EGBG-4S2#AC0 | FBGA (48) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0416EGBG-4S2#KC0 | FBGA (48) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMLV0416EGSB-4S2 | RMLV0416EGSB-4S2#AA1 | TSOP-II (44) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0416EGSB-4S2#HA1 | TSOP-II (44) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

低消費電力SRAMラインアップ (8Mb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|-----------------|---------|--------------------|-------------------|----------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.11μm Advanced | 8Mbit | 1M x 8 | RMLV0808BGSB-4S2 | RMLV0808BGSB-4S2#AA0 | TSOP-II (44) | Tray | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0808BGSB-4S2#HA0 | TSOP-II (44) | Tape & Reel | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 512K x 16 | RMLV0816BGBG-4S2 | RMLV0816BGBG-4S2#AC0 | FBGA (48) | Tray | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0816BGBG-4S2#KC0 | FBGA (48) | Tape & Reel | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 512K x 16 / 1M x 8 | RMLV0816BGSA-4S2 | RMLV0816BGSA-4S2#AA0 | TSOP-I (48) | Tray | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0816BGSA-4S2#KA0 | TSOP-I (48) | Tape & Reel | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 512K x 16 | RMLV0816BGSB-4S2 | RMLV0816BGSB-4S2#AA0 | TSOP-II (44) | Tray | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0816BGSB-4S2#HA0 | TSOP-II (44) | Tape & Reel | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 512K x 16 / 1M x 8 | RMLV0816BGSD-4S2 | RMLV0816BGSD-4S2#AA1 | μTSOP (52) | Tray | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV0816BGSD-4S2#HA1 | μTSOP (52) | Tape & Reel | 45ns | 2.4V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

低消費電力SRAMラインアップ (16Mb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|---------------------------|---------|---------------------|-------------------|----------------------|------------------|--------------|-------------|-------------------|-----------------------|-----------------|
| RMLV1616A-U series 開発中 | | 1M x 16 | RMLV1616AGBG-4U2 | RMLV1616AGBG-4U2#AC0 | FBGA (48) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | PLP登録 予定 (注) |
| | | | | RMLV1616AGBG-4U2#KC0 | FBGA (48) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| | | | RMLV1616AGBG-5U2 | RMLV1616AGBG-5U2#AC0 | FBGA (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| | | | | RMLV1616AGBG-5U2#KC0 | FBGA (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| 0.11μm Advanced | 16Mbit | 1M x 16 / 2M x 8 | RMLV1616AGSA-4U2 | RMLV1616AGSA-4U2#AA0 | TSOP-I (48) | Tray | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| | | | | RMLV1616AGSA-4U2#KA0 | TSOP-I (48) | Tape & Reel | 45ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| | | | RMLV1616AGSA-5U2 | RMLV1616AGSA-5U2#AA0 | TSOP-I (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| | | | | RMLV1616AGSA-5U2#KA0 | TSOP-I (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | |
| RMLV1616A-S series 量産中 | | 1M x 16 | RMLV1616AGBG-5S2 | RMLV1616AGBG-5S2#AC0 | FBGA (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV1616AGBG-5S2#KC0 | FBGA (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| 0.11μm Advanced | 16Mbit | 1M x 16 / 2M x 8 | RMLV1616AGSA-5S2 | RMLV1616AGSA-5S2#AA0 | TSOP-I (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV1616AGSA-5S2#KA0 | TSOP-I (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMLV1616AGSD-5S2 | RMLV1616AGSD-5S2#AA1 | μTSOP (52) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV1616AGSD-5S2#HA1 | μTSOP (52) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

注：RMLV1616A-Uシリーズは量産開始次第、他製品と同じPLP適用期間を登録予定です。

低消費電力SRAMラインアップ (32Mb~64Mb)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|-----------------|---------|------------------|-------------------|----------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.11μm Advanced | 32Mbit | 2M x 16 | RMWV3216AGBG-5S2 | RMWV3216AGBG-5S2#AC0 | FBGA (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMWV3216AGBG-5S2#KC0 | FBGA (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| 0.11μm Advanced | 32Mbit | 2M x 16 | RMLV3216AGBG-5S2 | RMLV3216AGBG-5S2#AC0 | FBGA (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV3216AGBG-5S2#KC0 | FBGA (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 2M x 16 / 4M x 8 | RMLV3216AGSA-5S2 | RMLV3216AGSA-5S2#AA0 | TSOP-I (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV3216AGSA-5S2#KA0 | TSOP-I (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMLV3216AGSD-5S2 | RMLV3216AGSD-5S2#AA0 | μTSOP (52) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMLV3216AGSD-5S2#HA0 | μTSOP (52) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| 0.11μm Advanced | 64Mbit | 4M x 16 | RMWV6416AGBG-5S2 | RMWV6416AGBG-5S2#AC0 | FBGA (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMWV6416AGBG-5S2#KC0 | FBGA (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | 4M x 16 / 8M x 8 | RMWV6416AGSA-5S2 | RMWV6416AGSA-5S2#AA0 | TSOP-I (48) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMWV6416AGSA-5S2#KA0 | TSOP-I (48) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | RMWV6416AGSD-5S2 | RMWV6416AGSD-5S2#AA0 | μTSOP (52) | Tray | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | RMWV6416AGSD-5S2#HA0 | μTSOP (52) | Tape & Reel | 55ns | 2.7V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |

高速SRAMラインアップ (4Mb, 5V)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|---------------|-----------------|--------------------|--------------------|---------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.18μm CMOS | 4Mbit | 512K x 8 | R1RP0408DGE-2LR | R1RP0408DGE-2LR#B1 | SOJ (36) | Magazine | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | - |
| | | | R1RP0408DGE-2PI | R1RP0408DGE-2PI#B1 | SOJ (36) | Magazine | 12ns | 4.5V ~ 5.5V | -40 ~ 85 °C | - |
| | | | R1RP0408DGE-2PR | R1RP0408DGE-2PR#B1 | SOJ (36) | Magazine | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | - |
| | | 256K x 16 | R1RP0416DGE-2LR | R1RP0416DGE-2LR#B1 | SOJ (44) | Magazine | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | - |
| | | | R1RP0416DGE-2PI | R1RP0416DGE-2PI#B1 | SOJ (44) | Magazine | 12ns | 4.5V ~ 5.5V | -40 ~ 85 °C | - |
| | | | R1RP0416DGE-2PR | R1RP0416DGE-2PR#B1 | SOJ (44) | Magazine | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | - |
| | | | R1RP0416DGE-2SR | R1RP0416DGE-2SR#B1 | SOJ (44) | Magazine | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | - |
| | | 256K x 16 | R1RP0416DSB-0PI | R1RP0416DSB-0PI#D1 | TSOP-II (44) | Tray | 10ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1RP0416DSB-0PR | R1RP0416DSB-0PR#D1 | TSOP-II (44) | Tray | 10ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 |
| | | | R1RP0416DSB-2LR | R1RP0416DSB-2LR#D1 | TSOP-II (44) | Tray | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 |
| | | | | R1RP0416DSB-2LR#S1 | TSOP-II (44) | Tape & Reel | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 |
| | | | R1RP0416DSB-2PI | R1RP0416DSB-2PI#D1 | TSOP-II (44) | Tray | 12ns | 4.5V ~ 5.5V | -40 ~ 85 °C | Dec. 2032 |
| | R1RP0416DSB-2PR | | R1RP0416DSB-2PR#D1 | TSOP-II (44) | Tray | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 | |
| | | | R1RP0416DSB-2PR#S1 | TSOP-II (44) | Tape & Reel | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 | |
| | R1RP0416DSB-2SR | R1RP0416DSB-2SR#D1 | TSOP-II (44) | Tray | 12ns | 4.5V ~ 5.5V | 0 ~ 70 °C | Dec. 2032 | | |

高速SRAMラインアップ (4Mb, 3.3V)

| Wafer Process | Density | Bit Org. | Catalog Part Name | Orderable Part Name | Package (pinout) | Packing Type | Access Time | Operating Voltage | Operating Temperature | PLP period |
|---------------|---------|-----------------|--------------------|---------------------|------------------|--------------|-------------|-------------------|-----------------------|------------|
| 0.18μm CMOS | 4Mbit | 512K x 8 | R1RW0408DGE-2LR | R1RW0408DGE-2LR#B1 | SOJ (36) | Magazine | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | - |
| | | | R1RW0408DGE-2PI | R1RW0408DGE-2PI#B1 | SOJ (36) | Magazine | 12ns | 3.0V ~ 3.6V | -40 ~ 85 °C | - |
| | | | R1RW0408DGE-2PR | R1RW0408DGE-2PR#B1 | SOJ (36) | Magazine | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | - |
| | | 256K x 16 | R1RW0416DGE-2LR | R1RW0416DGE-2LR#B1 | SOJ (44) | Magazine | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | - |
| | | | R1RW0416DGE-2PI | R1RW0416DGE-2PI#B1 | SOJ (44) | Magazine | 12ns | 3.0V ~ 3.6V | -40 ~ 85 °C | - |
| | | | R1RW0416DGE-2PR | R1RW0416DGE-2PR#B1 | SOJ (44) | Magazine | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | - |
| | | 256K x 16 | R1RW0416DSB-0PI | R1RW0416DSB-0PI#D1 | TSOP-II (44) | Tray | 10ns | 3.0V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1RW0416DSB-0PI#S1 | TSOP-II (44) | Tape & Reel | 10ns | 3.0V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1RW0416DSB-0PR | R1RW0416DSB-0PR#D1 | TSOP-II (44) | Tray | 10ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 |
| | | | | R1RW0416DSB-0PR#S1 | TSOP-II (44) | Tape & Reel | 10ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 |
| | | | R1RW0416DSB-2LR | R1RW0416DSB-2LR#D1 | TSOP-II (44) | Tray | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 |
| | | | R1RW0416DSB-2PI | R1RW0416DSB-2PI#D1 | TSOP-II (44) | Tray | 12ns | 3.0V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | | R1RW0416DSB-2PI#S1 | TSOP-II (44) | Tape & Reel | 12ns | 3.0V ~ 3.6V | -40 ~ 85 °C | Dec. 2032 |
| | | | R1RW0416DSB-2PR | R1RW0416DSB-2PR#D1 | TSOP-II (44) | Tray | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 |
| | | | | R1RW0416DSB-2PR#S1 | TSOP-II (44) | Tape & Reel | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 |
| | | R1RW0416DSB-2SR | R1RW0416DSB-2SR#D1 | TSOP-II (44) | Tray | 12ns | 3.0V ~ 3.6V | 0 ~ 70 °C | Dec. 2032 | |